



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IRFP7537PBF	<b>Issued</b>	21. July 2021
<b>MA#</b>	MA005540787		
<b>Package</b>	PG-TO247-3-901	<b>Weight*</b>	5730.09 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.335	0.13	0.13	1280	1280
leadframe	inorganic material	phosphorus	7723-14-0	1.131	0.02		197	
	non noble metal	iron	7439-89-6	3.771	0.07		658	
	non noble metal	copper	7440-50-8	3,765.728	65.72	65.81	657185	658040
wire	non noble metal	aluminium	7429-90-5	14.959	0.26	0.26	2611	2611
encapsulation	organic material	carbon black	1333-86-4	9.590	0.17		1674	
	plastics	epoxy resin	-	383.602	6.69		66945	
	inorganic material	silicondioxide	60676-86-0	1,524.819	26.61	33.47	266108	334727
leadfinish	non noble metal	tin	7440-31-5	13.948	0.24	0.24	2434	2434
solder	non noble metal	tin	7440-31-5	0.104			18	
	noble metal	silver	7440-22-4	0.130			23	
	non noble metal	lead	7439-92-1	4.970	0.09	0.09	867	908
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com